

## **Final Product Change Notification**

202208003F01: Final Test and Burn In Expansion to ASE-CL (Taiwan) for the FXTH87Exxxx Device Family

**Note:** This notice is NXP Company Proprietary.

Issue Date: Aug 12, 2022 Effective date: Nov 10, 2022

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#### **Management summary**

NXP is announcing the final test and burn in expansion from the current KES (Malaysia) site to the ASE-CL (Taiwan) site for the FXTH87Exxxx Device Family. The new site will use slightly different shipping labels, reels, and packing for the finished product.

#### **Change Category**

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[X]Packing/Shipping/Labeling	[X]Test Location	[]Electrical spec./Test coverage

# []Firmware []Other PCN Overview

## **Description**

NXP is announcing the final test and burn in expansion from the current KES (Malaysia) site to the ASE-CL (Taiwan) site for the FXTH87Exxxx Device Family. The new site will use slightly different shipping labels, reels, and packing for the finished product.

#### Reason

Test site expansion using the same test platform to improve manufacturing flexibility and customer supply assurance.

#### **Identification of Affected Products**

Product identification does not change

# **Product Availability**

#### Sample Information

Samples are available upon request

#### **Production**

Planned first shipment Nov 07, 2022

# Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

**Data Sheet Revision** 

No impact to existing datasheet

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

## **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Sep 11, 2022.

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Affected Part	Affected		
Numbers	12NC		
FXTH87EH11DT1	935340541528		
FXTH87EG02DT1	935340861528		
FXTH87EH02DT1	935340862528		
FXTH87EH116T1	935340863528		
FXTH87EG116T1	935340899528		
FXTH87EH118T1	935341038528		
FXTH87EH026T1	935341164528		
FXTH87EH226T1	935347007528		
FXTH87EG11DT1	935351532528		
FXTH87EG126T1	935351533528		
FXTH87EH12DT1	935351534528		
FXTH87EG026T1	935351828528		
FXTH87EH126T1	935351829528		
FXTH87EH018T1	935376366528		
FXTH87EH016T1	935381626528		
FXTH87EH219T1	935389706528		